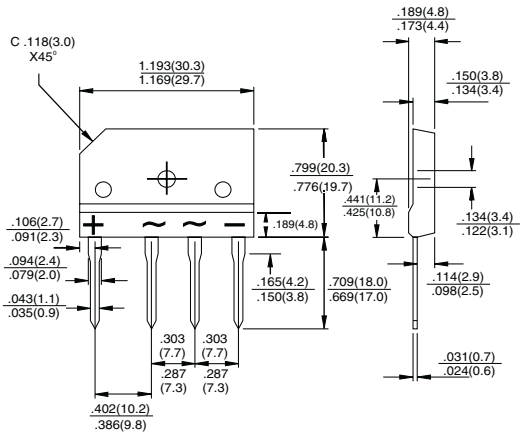
# 5.0 Amp. Glass Passivated Bridge

Plastic Case




## • Mounting Instructions

- High temperature soldering guaranteed: 260 ºC – 10 sc.
- Recommended mounting torque: 8 Kg.cm.

Voltage 400 to 1000

Current 5.0 A.

HYPERECTIFIER®

## • Glass Passivated Junction Chips.

- Lead and polarity identifications.
- Case: Molded Plastic.
- Ideal for printed circuit board (P.C.B.).
- High surge current capability.
- The plastic material carries U/L recognition 94 V-O.

## Maximum Ratings, according to IEC publication No. 134

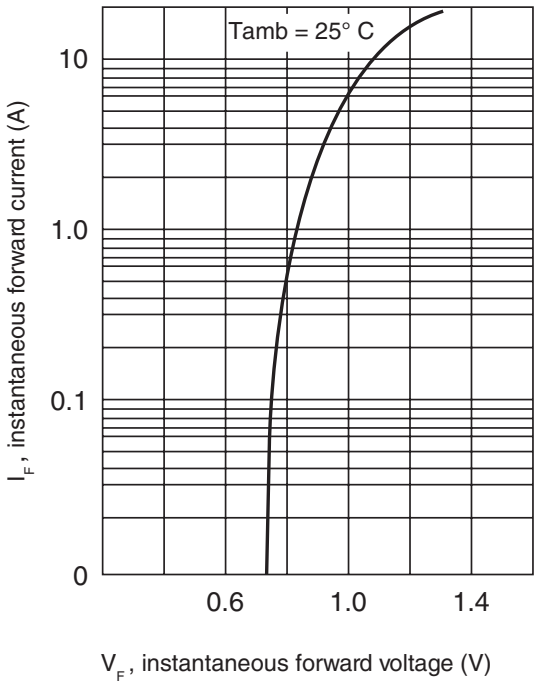
| | | D5XBA 40 | D5XBA 60 | D5XBA 80 | D5XBA 100 |
|---|---|---|---|---|---|
| $V_{RRM}$ | Peak recurrent reverse voltage (V) | 400 | 600 | 800 | 1000 |
| $V_{RMS}$ | Maximum RMS voltage (V) | 280 | 420 | 560 | 700 |
| $I_{F(AV)}$ | Max. Average forward current with heatsink<br>without heatsink | 5.0 A at Tc: 100 ºC<br>2.8 A at 25 ºC | | | |
| $I_{FSM}$ | 10 ms. peak forward surge current (Jedec Method) | 150 A | | | |
| $V_{DIS}$ | Dielectric strength (terminals to case, AC 1 min.) | 2500 V | | | |
| $I^2t$ | $I^2t$ value for fusing (t = 10 ms) | 93 $A^2$sec | | | |
| $T_j$ | Operating temperature range | – 40 to + 150 °C | | | |
| $T_{stg}$ | Storage temperature range | – 40 to +150 °C | | | |

## Electrical Characteristics at Tamb = 25°C

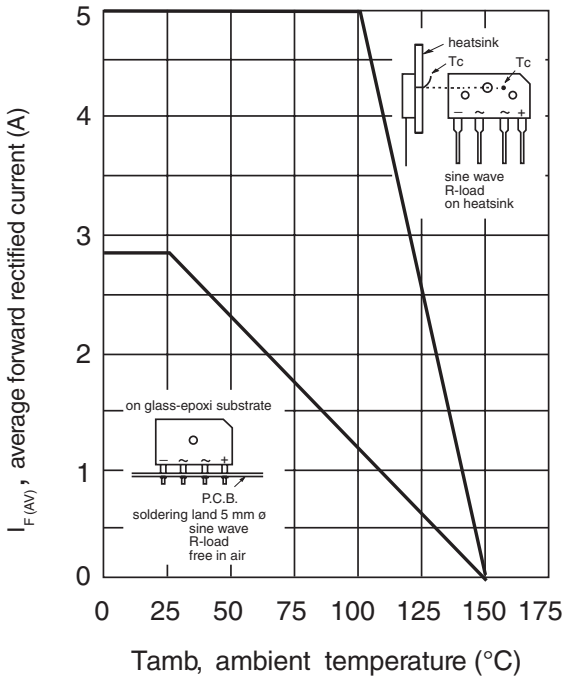
| | | |
|---|---|---|
| $V_F$ | Max. forward voltage drop per diode at $I_F$ = 3.0 A | 1.00 V |
| $I_R$ | Max. instantaneous reverse current at $V_{RRM}$ | 5 µA |
| | MAXIMUM THERMAL RESISTANCE | |
| $R_{th\ (j-c)}$ | Junction-Case. With Heatsink. | 3.4 ºC/W |
| $R_{th\ (j-a)}$ | Junction-Ambient. Without Heatsink. | 22 ºC/W |

## Rating And Characteristic Curves

TYPICAL FORWARD CHARACTERISTIC




FORWARD CURRENT DERATING CURVE




MAXIMUM NON-REPETITIVE PEAK
FORWARD SURGE CURRENT